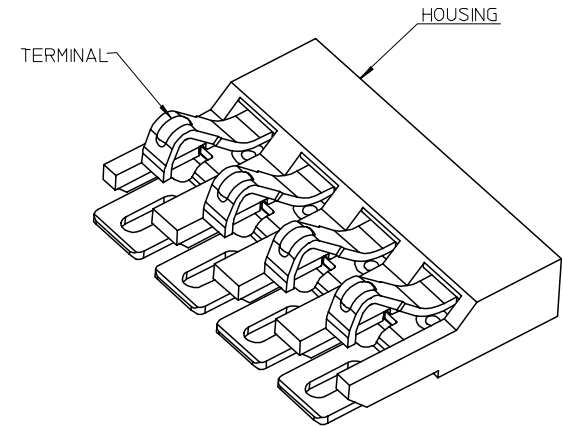
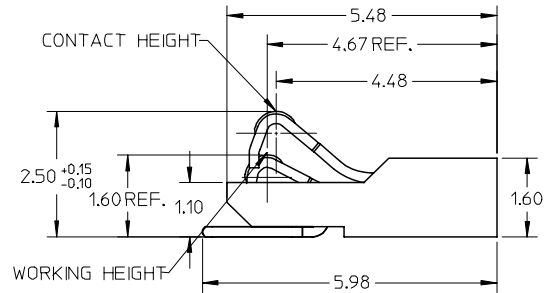
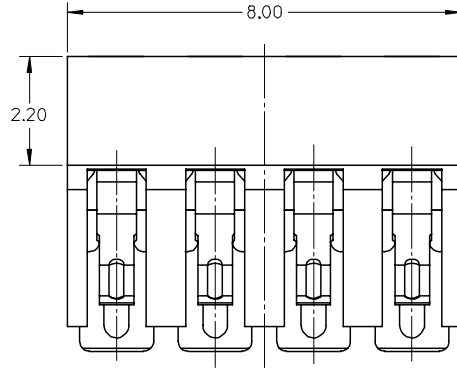


10 9 8 7 6 5 4 3 2 1

F

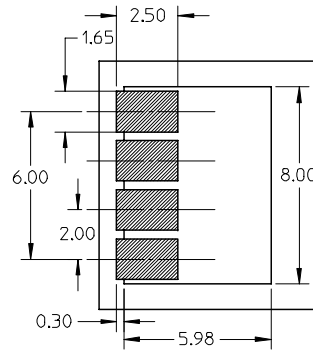
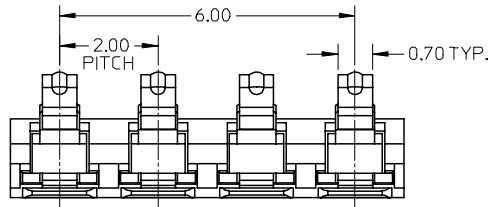


E

F

E

D



NOTE:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC,COLOR:BLACK
TERMINAL: COPPER ALLOY

2.FINISH:

CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.
SOLDER AREA: GOLD FLASH (0.075~0.125 MICRON) OVER 1.25 MICRON NICKEL MIN.
REST AREA: 1.25 MICRON NICKEL MIN.

3.COPLANARITY: 0.1 MAX AMONG THESE SOLDER TAILS.

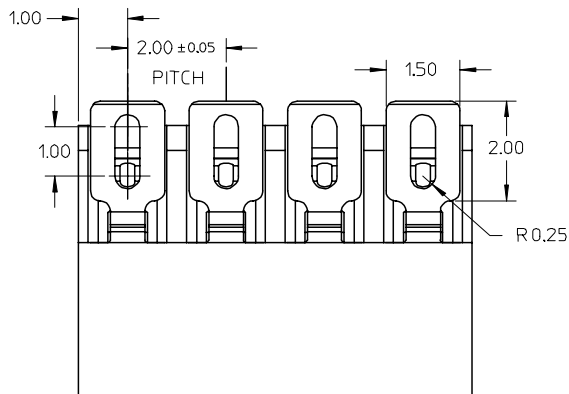
4.PRODUCT SPECIFICATION: PS-47286-001

5.RECOMMENDED WORKING DEFLECTION RANGE:0.6-1.00 MM

D

C

C



B

B

A

A

REVISE	EC NO: D 2006/09/08 DRWN: LSHEN CHKD: XU APPR: JCHEN 2006/10/17 2006/11/16	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
					mm	INCH	DRAWN BY SSUN	DATE 2005/07/29	TITLE 2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR	
				4 PLACES	± ---	± ---	CHECKED BY XUXIANG	DATE 2006/07/06		
				3 PLACES	± ---	± ---	APPROVED BY JENNY CHEN	DATE 2006/07/07		
				2 PLACES	± 0.15	± ---	MOLEX INCORPORATED			
				1 PLACE	± 0.20	± ---	MATERIAL NO. 472861001		DOCUMENT NO. SD-47286-001	SHEET NO. 1 OF 1
				ANGULAR ± 2 °						
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		